

FEATURES

- TrenchFET Power MOSFET
- 100% R_G tested
- High Current and Power handing capability



Product Summary			
V _{DS}	R _{D(on)} (mΩ) Typ	I _D (A)	Q _g (Typ)
20V	13.5 @ 4.5V	6.8	9.2nC
	17.0 @ 2.5V	3.0	
	27.0 @ 2.5V	2.5	

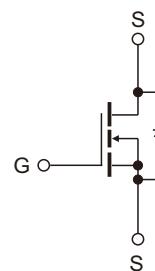
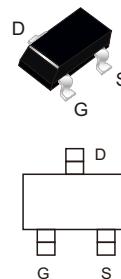
APPLICATIONS

- Load Switch
- Power Management
- PWM Control Circuit

MECHANICAL DATA

- Case:SOT-23(TO-236)
- Terminals:Plated solderable per MIL-STD-750,method 2026
- Mounting Position: Any

SOT-23



N-channel MOSFET

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameters	Symbol	Value	Unit
Drain-Source voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±10	V
Continuous Drain Current (T _J = 150°C)	T _A =25°C	6.8	A
	T _A =70°C	5.4	
Pulsed Drain Current ¹⁾	I _{DM}	27	A
Maximum Power Dissipation @T _A =25°C	P _D	1.2	W
Junction and Storage Temperature Range	T _J ,T _{STG}	-55 to +150	°C

Thermal Resistance Ratings

Parameters	Symbol	Typ	Max	Unit
Junction to Ambient, Steady State ²⁾	R _{θJA}	-	104	°C/W

RATINGS AND CHARACTERISTIC OF JH2312A

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameters	Symbol	Conditions	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, T_c=25^\circ\text{C}$	-	-	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 10\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}= V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.45	0.62	1	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=6.8\text{A}$	-	13.5	18	$\text{m}\Omega$
		$V_{\text{GS}}= 2.5\text{V}, I_{\text{D}}=3.0\text{A}$	-	17	22	
		$V_{\text{GS}}= 1.8\text{V}, I_{\text{D}}=2.5\text{A}$	-	27	39	
Dynamic						
Input Capacitance	C_{iss}	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	900	-	pF
Output Capacitance	C_{oss}		-	165	-	
Reverse Transfer Capacitance	C_{rss}		-	75	-	
Total Gate Charge	Q_g	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=6.8\text{A}$	-	900	-	nc
Gate-Source Charge	Q_{gs}		-	165	-	
Gate-Drain Charge	Q_{gd}		-	75	-	
Turn-on Delay Time	$t_{\text{D}(\text{on})}$	$V_{\text{GS}}=4.5\text{V}, V_{\text{DD}}=10\text{V}, R_{\text{L}}=1.5\Omega, R_{\text{GEN}}=3\Omega$	-	12	-	ns
Rise Time	t_r		-	52	-	
Turn-off Delay Time	$t_{\text{D}(\text{off})}$		-	17	-	
Fall Time	t_f		-	10	-	
Drain-Source Body Diode Characteristics						
Maximum Body-Diode Continuous Current	I_s		-	-	6.8	A
Diode Forward Voltage	V_{SD}	$I_s=6.8\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.2	V

Notes: 1. Pulse Test: Pulse Width $\leq 300\text{us}$, Duty cycle $\leq 2\%$.

2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

RATINGS AND CHARACTERISTIC OF JH2312A

Typical Performance Characteristics

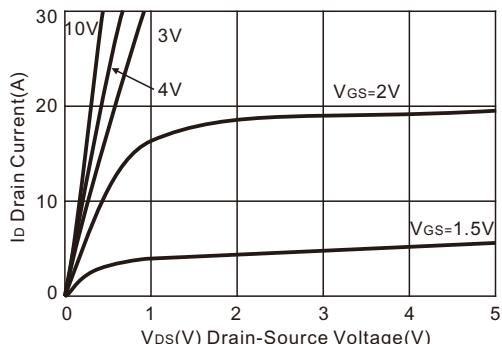


Fig1. Output Characteristics

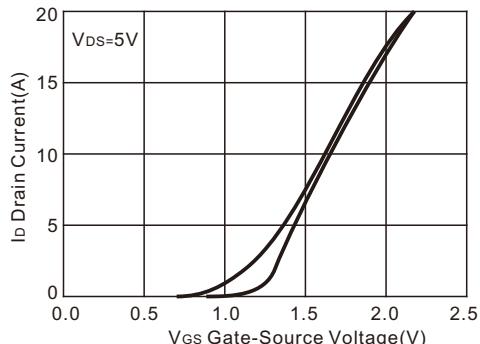


Fig2. Transfer Characteristics

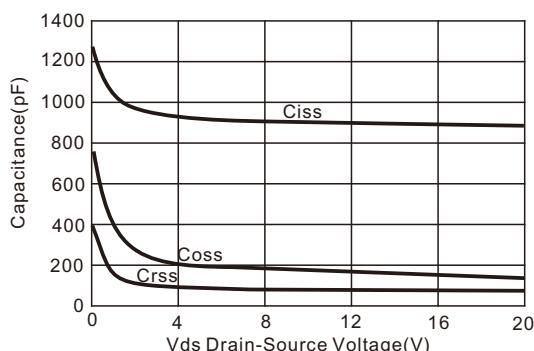


Fig3. Capacitance Characteristics

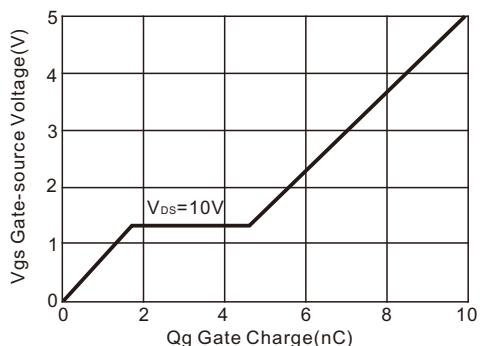


Fig4. Gate Charge

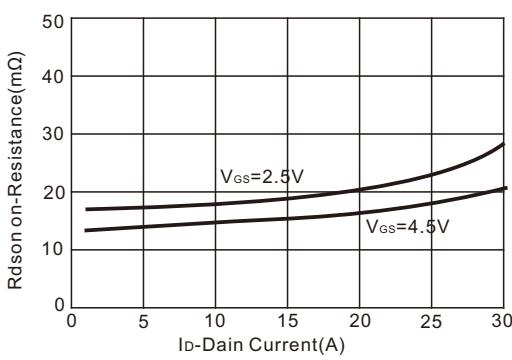


Fig5. Drain-Source on Resistance

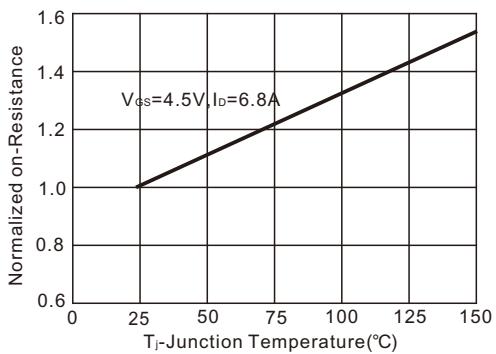


Fig6. Drain-Source on Resistance

RATINGS AND CHARACTERISTIC OF JH2312A

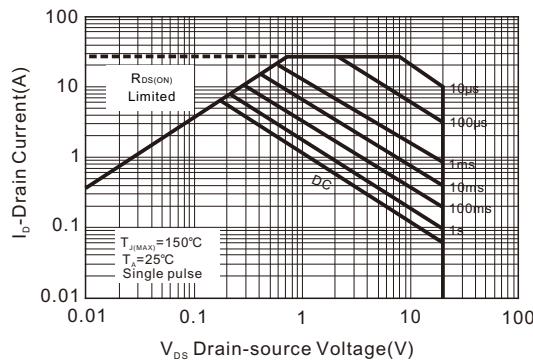


Fig7. Safe Operation Area

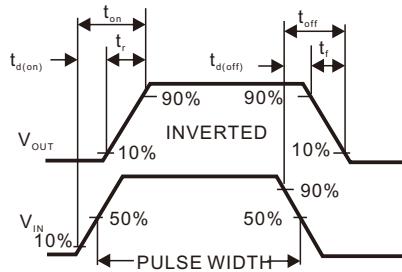
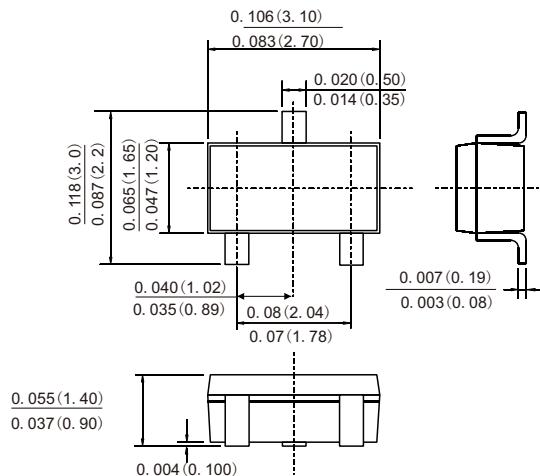


Fig8. Switching wave

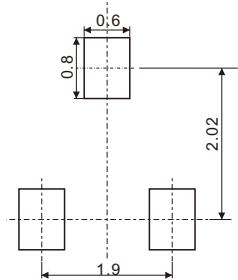
PACKAGE OUTLINE DIMENSIONS

SOT-23



Dimensions in inches and (millimeters)

Suggested Pad Layout



Dimensions in millimeters